

Title (en)
PHOTOSENSITIVE COMPOSITIONS AND APPLICATIONS THEREOF

Title (de)
FOTOEMPFLINDLICHE ZUSAMMENSETZUNGEN UND ANWENDUNGEN DAVON

Title (fr)
COMPOSITIONS PHOTOSENSIBLES ET LEURS APPLICATIONS

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Abstract (en)
[origin: WO2021076131A1] The present invention relates to photosensitive compositions containing polynorbornene (PNB) polymers and certain additives that are useful for forming microelectronic and/or optoelectronic devices and assemblies thereof, and more specifically to compositions encompassing PNBs and certain multifunctional crosslinking agents, and two or more phenolic compounds which are resistant to thermo-oxidative chain degradation and exhibit improved mechanical properties.

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